



# DCR690G52

# **Phase Control Thyristor**

Replaces DS5830-4 DS5830-5 September 2024 (LN43593)

#### **FEATURES**

- Double Side Cooling
- High Surge Capability

#### **APPLICATIONS**

- High Power Drives
- High Voltage Power Supplies
- Static Switches

#### **VOLTAGE RATINGS**

Part and Ordering Number	Repetitive Peak Voltages VDRM and VRRM (V)	Conditions
DCR690G52* DCR690G50 DCR690G48	5200 5000 4800	$T_{Vj} = -40 ^{\circ} C \text{ to } 125 ^{\circ} C,$ $IDRM = IRRM = 100 mA,$ $VDRM, VRRM t_{P} = 10 ms$ $VDSM \& VRSM =$ $VDRM \& VRRM + 100 V$ $respectively$

Lower voltage grades available.

#### **ORDERING INFORMATION**

When ordering, select the required part number shown in the Voltage Ratings selection table.

For example:

#### DCR690G52

Note: Please use the complete part number when ordering and quote this number in any future correspondence relating to your order.

#### **KEY PARAMETERS**

<b>V</b> DRM	5200V
I <sub>T(AV)</sub>	690A
Ітѕм	9450A
dV/dt*	1500V/µs
dl/dt	300A/μs

<sup>\*</sup>Higher dV/dt selections are available on request

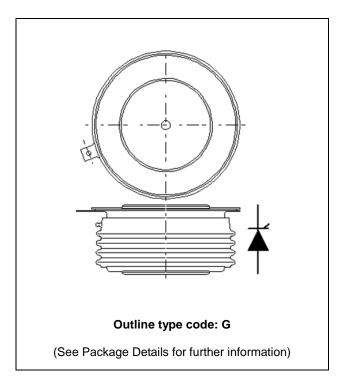


Fig. 1 Package outline

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<sup>\*5000</sup>V @ -40°C, 5200V @ 0°C



## **CURRENT RATINGS**

## T<sub>case</sub> = 60°C unless stated otherwise

Symbol Parameter		Test Conditions	Max.	Units
Double Side Cooled				
IT(AV)	Mean on-state current	Half wave resistive load	690	А
IT(RMS)	RMS value	-	1080	А
lτ	Continuous (direct) on-state current	-	1060	А

## **SURGE RATINGS**

Symbol	Parameter	Test Conditions	Max.	Units
Ітѕм	Surge (non-repetitive) on-state current	10ms half sine, Tcase = 125°C	9.45	kA
l²t	I2t for fusing	V <sub>R</sub> = 0	0.45	MA <sup>2</sup> s

## THERMAL AND MECHANICAL RATINGS

Symbol	Parameter	Test Conditions		Min.	Max.	Units
		Double side cooled	DC	-	26.8	°C/kW
Rth(j-c)	Thermal resistance - junction to case	Cingle side socied	Anode DC	-	52.7	°C/kW
		Single side cooled	Cathode DC	-	65.2	°C/kW
Date	Thermal resistance - case to heatsink	Clamping force 11.5kN	Double side	-	7.2	°C/kW
Rth(c-h)		(with mounting compound)	Single side	-	14.4	°C/kW
Tvj	Tvj Virtual junction temperature Blocking VDRM / VRRM		-	125	°C	
Tstg	Storage temperature range			-55	125	°C
Fm	Clamping force			10	13	kN

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## **DYNAMIC CHARACTERISTICS**

Symbol	Parameter	Test Condition	Test Conditions		Max.	Units
IRRM/IDRM	Peak reverse and off-state current	At VRRM/VDRM, Tcase = 125°C		-	100	mA
Vтм	Instantaneous forward voltage	At 1600A peak, Tj = 25°C		2.10	2.40	V
dV/dt	Max. linear rate of rise of off-state voltage	To 67% V <sub>DRM</sub> , T <sub>j</sub> = 125°C, g	ate open	-	1500	V/µs
dl/dt	Rate of rise of on-state current	From 67% V <sub>DRM</sub> to $2x I_{T(AV)}$ Gate source $30V$ , $10\Omega$	Repetitive 50Hz	-	150	A/µs
	Trace of the of the oracle outlies.	, , , , , , , , , , , , , , , , , , ,	Non-repetitive	-	300	A/µs
.,	Threshold voltage - Low level	100A to 500A at Tcase = 125°C		-	0.92	V
<b>V</b> т(то)	Threshold voltage - High level	500A to 3000A at Tcase = 125°C		-	1.10	٧
_	On-state slope resistance - Low level	100A to 500A at Tcase = 125°C		-	1.45	mΩ
ľΤ	On-state slope resistance - High level	500A to 3000A at Tcase = 125°C		-	1.12	mΩ
tgd	Delay time	$V_D = 67\% \ V_{DRM}, \ gate \ source \ 30V, \ 10\Omega$ $t_T = 0.5 \mu s, \ T_j = 25 ^{\circ} C$		-	3	μs
tq	Turn-off time	$T_j = 125$ °C, $V_R = 200$ V, $dI/dt = 5$ A/ $\mu$ s, $dV_{DR}/dt = 20$ V/ $\mu$ s linear		400	800	μs
Qs	Stored charge [LEM]	Iτ = 2000A, Tj = 125°C, dl/dt = 5A/μs		1200	2400	μC
Qs	Stored charge	T <sub>j</sub> = 125°C, dl/dt = 1A/μs,		-	2170	μC
IRR	Reverse recovery current	VR peak ~ 3200V, VR ~ 2600V		-	37	А
<b>I</b> L	Latching current	Tj = 25°C, VD = 5V		-	3	А
lн	Holding current	Tj = 25°C, Rg-κ = ∞, Iтм = 500A, Iт = 5A		-	300	mA

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#### **GATE TRIGGER CHARACTERISTICS AND RATINGS**

Symbol	Parameter	Test Conditions	Max.	Units
Veт Gate trigger voltage VDRM = 5V, Tcase = 25°C		VDRM = 5V, Tcase = 25°C	1.5	V
V <sub>GD</sub> Gate non-trigger voltage		At 50% VDRM, Tcase = 125°C	0.4	V
Iст Gate trigger current		VDRM = 5V, Tcase = 25°C	350	mA
IGD	Gate non-trigger current	At 50% VDRM, Tcase = 125°C	10	mA

#### **CURVES**

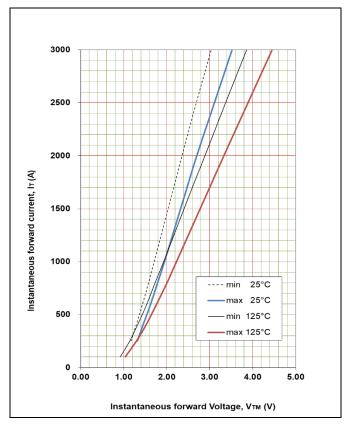


Fig. 2 Maximum & minimum on state characteristics

## **VTM EQUATION**

 $V_{TM} = A + B.ln(I_T) + C.I_T + D.\sqrt{I_T}$ 

Where A = 0.207302

B = 0.178990

C = 0.001121

D = -0.010408

These values are valid for  $T_j = 125$ °C for  $I_T 100A$  to 3000A

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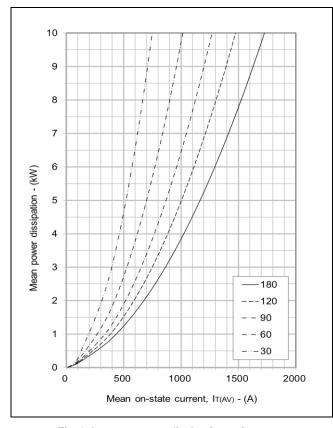


Fig. 3 On-state power dissipation - sine wave

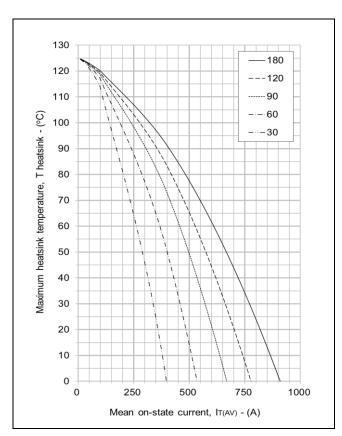


Fig. 5 Maximum permissible heatsink temperature, double side cooled - sine wave

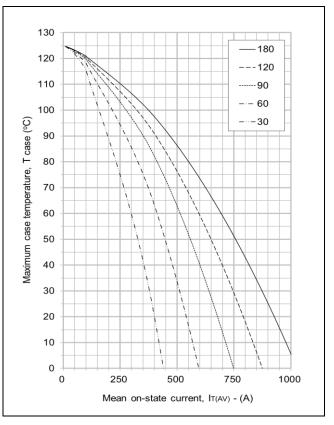


Fig. 4 Maximum permissible case temperature, double side cooled - sine wave

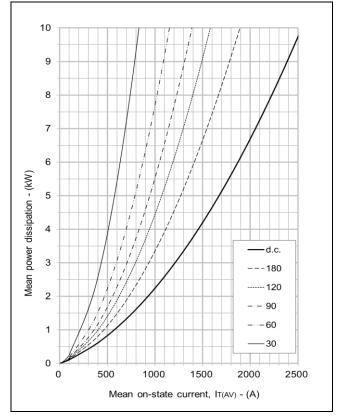


Fig. 6 On-state power dissipation - rectangular wave

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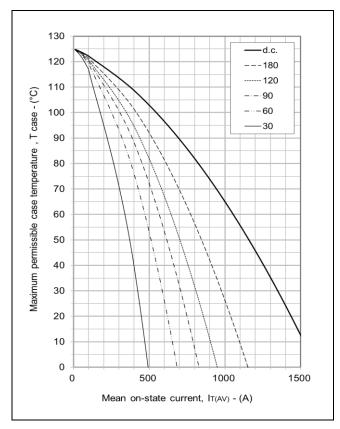
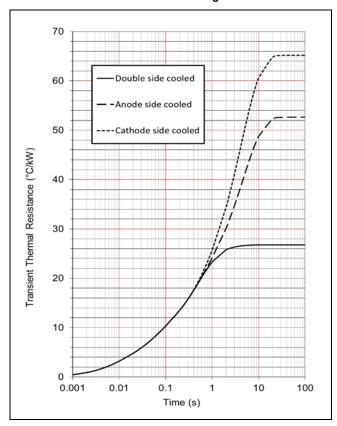


Fig. 7 Maximum permissible case temperature, double side cooled - rectangular wave



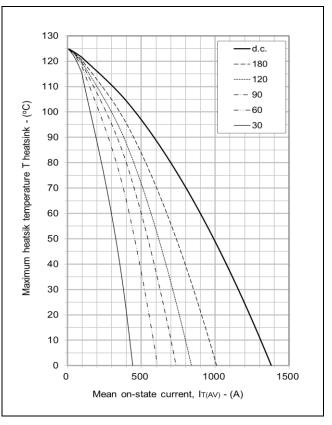


Fig. 8 Maximum permissible heatsink temperature, double side cooled - rectangular wave

		1	2	3	4
Double side	Ri(°C/kW)	2.300	5.423	16.907	2.149
cooled	Ti(s)	0.007	0.046	0.496	1.825
Anode side	Ri(°C/kW)	2.321	5.266	10.269	34.803
cooled	Ti(s)	0.007	0.046	0.348	4.582
Cathode side	Ri(°C/kW)	2.490	5.911	7.426	49.343
cooled	Ti(s)	0.007	0.053	0.393	4.230

$$Z_{th} = \sum_{i=1}^{i=4} R_i \cdot \left(1 - \exp\left(-\frac{T}{T_i}\right)\right)$$

 $\Delta R_{\text{th(j-c)}}$  Conduction

Tables show the increments of thermal resistance R  $_{\text{th(j-c)}}$  when the device operates at conduction angles other than d.c.

	Double side α	ooling		
	$\Delta Z_{th}$ (z)			
6°	sine. rect.			
180	4.15	2.72		
120	4.90	4.02		
90	5.74	4.79		
60	6.53	5.65		
30	7.16	6.64		
15	7.46	7 12		

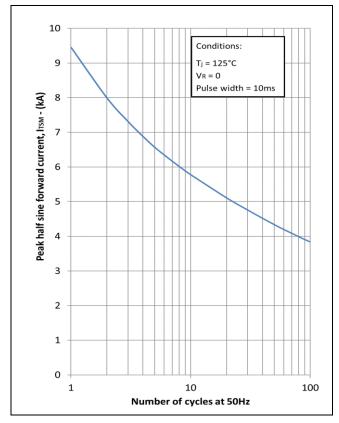
		Alloge Side Cooling				
]		ΔZ <sub>th</sub> (z)				
]	θ°	sine.	rect.			
]	180	4.15	2.72			
	120	4.89	4.02			
	90	5.73	4.78			
]	60	6.52	5.65			
	30	7.15	6.62			
1	4.5	7.44	7.40			

	Anode Side Cooling			Ca	Cooling	
	$\Delta Z_{th}$ (z)				h (Z)	
θ°	sin e.	rect.		θ°	sine.	rect.
180	4.15	2.72		180	4.13	2.71
120	4.89	4.02		120	4.87	4.00
90	5.73	4.78		90	5.69	4.76
60	6.52	5.65		60	6.46	5.60
30	7.15	6.62		30	7.07	6.56
15	7.44	7.16		15	7.36	7.09

Fig. 9 Maximum (limit) transient thermal impedance - junction to case (degC/kW)

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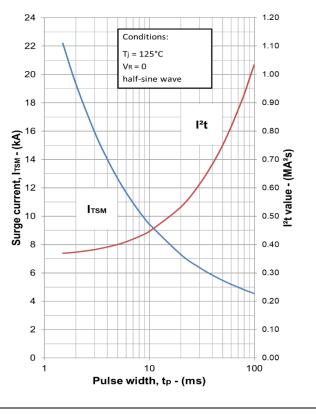


Fig. 10 Multi-cycle surge current

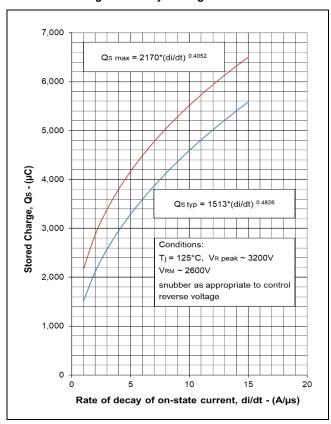


Fig. 12 Stored charge

Fig. 11 Single-cycle surge current

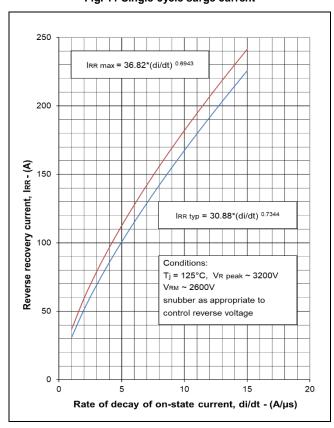


Fig. 13 Reverse recovery current

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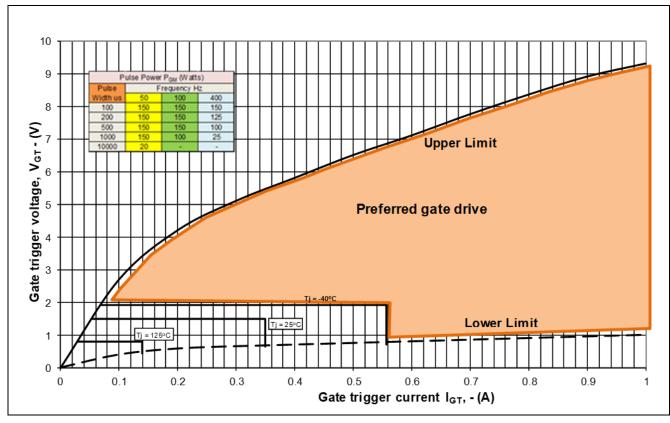


Fig. 14 Gate characteristics

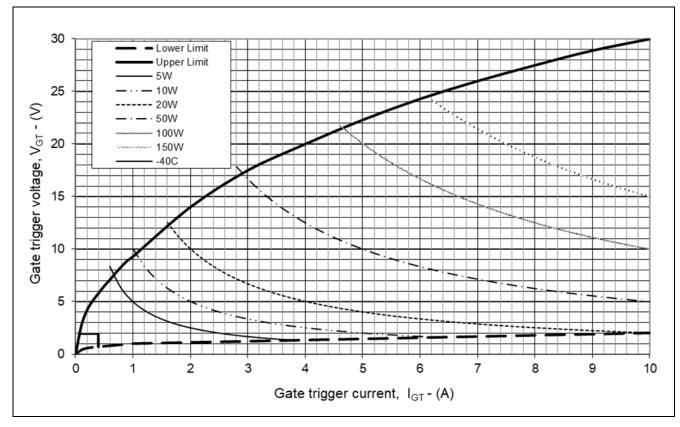


Fig. 15 Gate characteristics

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#### **PACKAGE DETAILS**

For further package information, please contact Customer services.

All dimensions in mm, unless stated otherwise.

DO NOT SCALE

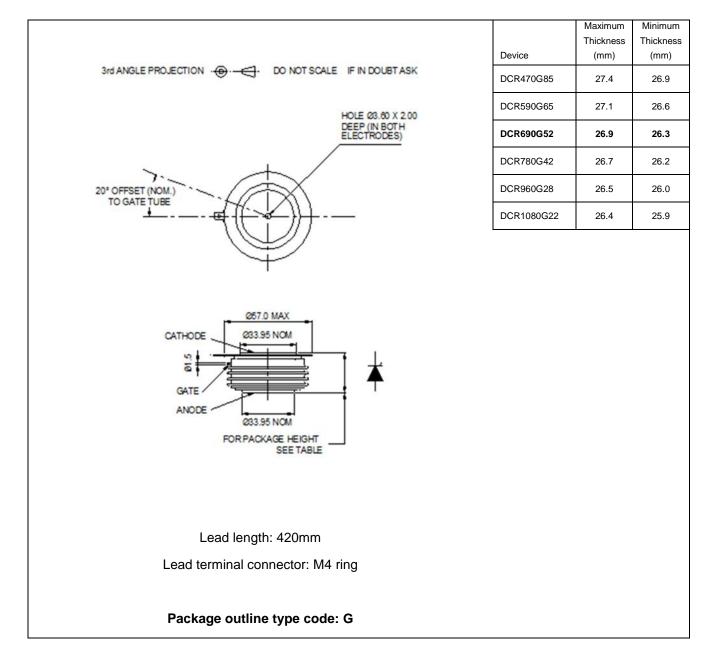


Fig. 16 Package outline

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